

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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HIGH DENSITY MOUNTING PHOTOTRANSISTOR OPTICALLY COUPLED ISOLATORS



DESCRIPTION

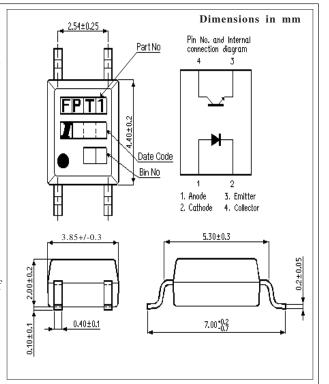
The IS2701-1 is an optically coupled isolator consisting of an infrared light emitting diode and NPN silicon photo transistor in a space efficient dual in line plastic package.

FEATURES

- Marked as FPT1.
- Current Transfer Ratio MIN. 50%
- $Isolation Voltage (3.75kV_{RMS}, 5.3kV_{PK}) \\ All electrical parameters 100\% tested$
- Drop in replacement for NEC PS2701-1

APPLICATIONS

- Computer terminals
- Industrial systems controllers
- Measuring instruments
- Signal transmission between systems of different potentials and impedances



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ABSOLUTEMAXIMUMRATINGS (25°C unless otherwise specified)

Storage Temperature	-55°C to $+150$ °C
Operating Temperature	-55°C to $+ 100$ °C
Lead Soldering Temperature	
(1/16 inch (1.6mm) from case for 10) secs) 260°C

INPUTDIODE

Forward Current	50mA
Reverse Voltage	6V
Power Dissipation	70mW

OUTPUTTRANSISTOR

Collector-emitter Voltage BV _{CEO}	80V
Emitter-collector Voltage BV _{ECO}	6V
Collector Current	50mA
Power Dissipation	150mW

POWERDISSIPATION

Total Power Dissipation	170mW
(derate linearly 2.26mW/°C above 25°C)	

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ Unless otherwise noted)

	PARAMETER	MIN	TYP	MAX	UNITS	TEST CONDITION
Input	Forward Voltage (V_F)		1.2	1.4	V	$I_F = 20 \text{mA}$
	Reverse Current (I_R)			10	μА	$V_R = 4V$
Output	Collector-emitter Breakdown (BV $_{\text{CEO}}$)	80			V	$I_{\rm C}$ =0.1mA
	$Emitter-collector Breakdown (BV_{ECO} \\ Collector-emitter Dark Current (I_{CEO})$) 6		100	V nA	$I_{\scriptscriptstyle E} = 10 \mu A \\ V_{\scriptscriptstyle CE} = 20 V$
Coupled	Current Transfer Ratio (CTR)	50		600	%	$5\text{mAI}_{\scriptscriptstyle F}, 5\text{VV}_{\scriptscriptstyle \text{CE}}$
	1 1 150	80 130 200 300 200 3750 5300		160 260 400 600 0.2 V _{RMS}	% % % % V V	$\begin{array}{l} 5\text{mA}I_{\text{F}},5\text{V}V_{\text{CE}} \\ 5\text{mA}I_{\text{F}},5\text{V}V_{\text{CE}} \\ 5\text{mA}I_{\text{F}},5\text{V}V_{\text{CE}} \\ 5\text{mA}I_{\text{F}},5\text{V}V_{\text{CE}} \\ 5\text{mA}I_{\text{F}},5\text{V}V_{\text{CE}} \\ 20\text{mA}I_{\text{F}},1\text{mA}I_{\text{C}} \\ \end{array}$ See note 1
	Input-output Isolation Resistance R_{ISO} Output Rise Time tr Output Fall Time tf	5x10 ¹⁰	4 3	18 18	Ω μs μs	$V_{IO} = 500 \text{V (note 1)}$ $V_{CE} = 2 \text{V ,}$ $I_{C} = 2 \text{mA ,} R_{L} = 100 \Omega$

Note 1 Measured with input leads shorted together and output leads shorted together.

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